

EDOP400-x

400G OSFP112 Direct Attach Cable (DAC)

PRODUCT FEATURES

- Compatible with IEEE 802.3ck
- Supports aggregate data rates of 400Gbps(PAM4)
- Optimized construction to minimize insertion loss and crosstalk
- Pull-to-release slide latch design
- Straight and break out assembly configurations available
- Customized cable braid termination limits EMI radiation
- Customizable EEPROM mapping for cable signature
- 26AWG and 30AWG cable
- 3.3V Power supply
- Temperature Range: 0~ 70 °C
- RoHs Compliant

APPLICATIONS

- Switches, servers and routers
- Data Center networks
- Storage area networks
- High performance computing
- Telecommunication and wireless infrastructure
- Medical diagnostics and networking
- Test and measurement equipment

INDUSTRY STANDARDS

- 400G Ethernet(IEEE 802.3ck)
- InfiniBand NDR

DESCRIPTIONS

400G OSFP112 passive copper cable assembly feature eight differential copper pairs, providing four data transmission channels at speeds up to 100Gbps(PAM4) per channel, and meets 400G Ethernet and InfiniBand Next Data Rate(NDR) requirements. Available in 26AWG and 30AWG wire gauges, this 400G copper cable assembly features low insertion loss and low crosstalk.

OSFP112 passive copper cable uses PAM4 signals for transmission, which doubles the rate. However, there are more stringent requirements for cable insertion loss. For detailed requirements, please see High Speed Characteristics.

Ordering Information

Part No.	Description
EDOQ400-x-30	400G OSFP112 Direct Attach Cable AWG30 0~1M
EDOQ400-x-26	400G OSFP112 Direct Attach Cable AWG30 1.5~2M

Notes:

- where "x" denotes cable length in meters. Examples are as follows:
- x = 0.5 for 0.5m, x=1 for 1m

General Product Characteristics

OSFP112 DAC Specifications	
Number of Lanes	Tx4 & Rx4
Channel Data Rate	106.25Gbps
Operating Temperature	0 to + 70°C
Storage Temperature	-40 to + 85°C
Supply Voltage	3.3 V nominal
Electrical Interface	60pins edge connector
Management Interface	Serial, I ² C

High Speed Characteristics

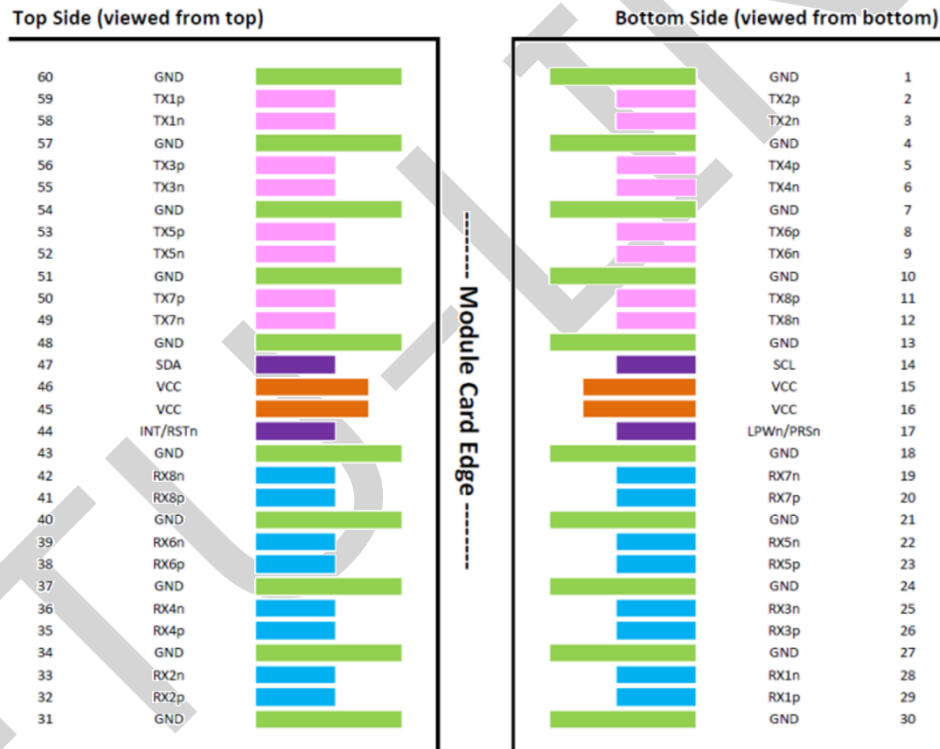
Parameter	Symbol	Min	Typical	Max	Unit	Note
Differential Impedance	TDR	90	100	110	Ω	
Insertion loss	SDD21	-19.75			dB	At 26.56 GHz
Differential Return Loss	SDD11 SDD22			See 1	dB	At 0.05 to 26.56GHz
				See 2	dB	At 26.56 to 40 GHz

Common-mode to common-mode output return loss	SCC11 SCC22			-1.8	dB	At 0.2 to 40GHz
Differential to common Mode Conversion Loss	SCD21- SDD21			-10	dB	At 0.05 to 12.89 GHz
				See3		At 12.89 to 40 GHz

Notes:

1. Reflection Coefficient given by equation $SDD11(dB) < 22 - 10(f/26.56)$, with f in GHz
2. Reflection Coefficient given by equation $SDD11(dB) < 15 - 3(f/26.5)$, with f in GHz
3. Reflection Coefficient given by equation $SCD21-CDD21(dB) < 14 - 0.3108*f$, with f in GHz

Pin Diagram



Pin Definitions

OSFP112 Pin Function Definition

Pin	Logic	Symbol	Description
1		GND	Ground
2	CML-I	Tx2p	Transmitter Non-Inverted Data Input
3	CML-I	Tx2n	Transmitter Inverted Data Input
4		GND	Ground

5	CML-I	Tx4p	Transmitter Non-Inverted Data Input
6	CML-I	Tx4n	Transmitter Inverted Data Input
7		GND	Ground
8	CML-I	Tx6p	Transmitter Non-Inverted Data Input
9	CML-I	Tx6n	Transmitter Inverted Data Input
10		GND	Ground
11	CML-I	Tx6p	Transmitter Non-Inverted Data Input
12	CML-I	Tx6n	Transmitter Inverted Data Input
13		GND	Ground
14	LVC MOS-I/O	SCL	2-wire serial interface clock
15		VCC	+3.3V Power supply
16		VCC	+3.3V Power supply
17		LPWn/PRSn	Low-Power Mode / Module Present
18		GND	Ground
19	CML-O	Rx7n	Receiver Inverted Data Output
20	CML-O	Rx7p	Receiver Non-Inverted Data Output
21		GND	Ground
22	CML-O	Rx5n	Receiver Inverted Data Output
23	CML-O	Rx5p	Receiver Non-Inverted Data Output
24		GND	Ground
25	CML-O	Rx3n	Receiver Inverted Data Output
26	CML-O	Rx3p	Receiver Non-Inverted Data Output
27		GND	Ground
28	CML-O	Rx1n	Receiver Inverted Data Output
29	CML-O	Rx1p	Receiver Non-Inverted Data Output
30		GND	Ground
31		GND	Ground
32	CML-O	Rx2p	Receiver Non-Inverted Data Output
33	CML-O	Rx2n	Receiver Inverted Data Output
34		GND	Ground
35	CML-O	Rx4p	Receiver Non-Inverted Data Output
36	CML-O	Rx4n	Receiver Inverted Data Output
37		GND	Ground
38	CML-O	Rx6p	Receiver Non-Inverted Data Output
39	CML-O	Rx6n	Receiver Inverted Data Output
40		GND	Ground
41	CML-O	Rx8p	Receiver Non-Inverted Data Output
42	CML-O	Rx8n	Receiver Inverted Data Output
43		GND	Ground
44		INT/RSTn	Module Interrupt / Module Reset
45		VCC	+3.3V Power supply
46		VCC	+3.3V Power supply
47	LVC MOS-I/O	SDA	2-wire serial interface data
48		GND	Ground
49	CML-I	Tx7n	Transmitter Inverted Data

50	CML-I	Tx7p	Input Transmitter Non-Inverted Data Input
51		GND	Ground
52	CML-I	Tx5n	Transmitter Inverted Data
53	CML-I	Tx5p	Input Transmitter Non-Inverted Data Input
54		GND	Ground
55	CML-I	Tx3n	Transmitter Inverted Data
56	CML-I	Tx3p	Input Transmitter Non-Inverted Data Input
57		GND	Ground
58	CML-I	Tx1n	Transmitter Inverted Data
59	CML-I	Tx1p	Input Transmitter Non-Inverted Data Input
60		GND	Ground

Recommended Interface Circuit

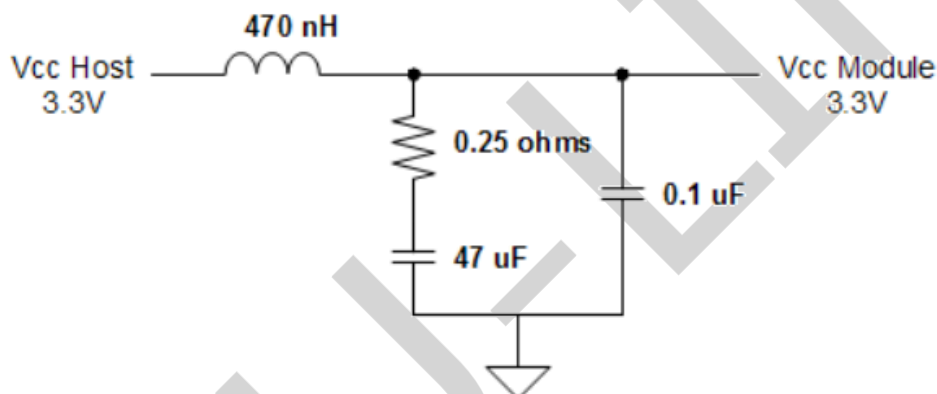
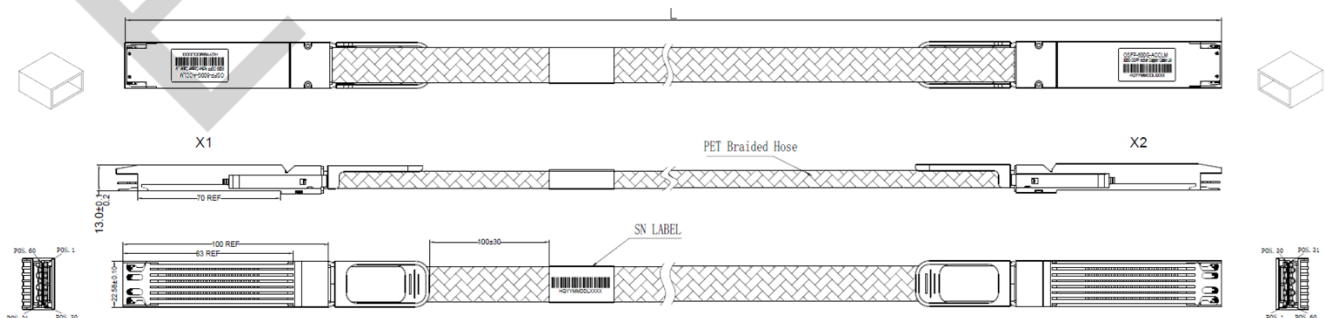


Figure 13-6: Host board power filter circuit

Mechanical Diagram

The connector is compatible with the SFF8024 specification.



Length (m)	Cable AWG	OD(MM)
1	30	10.0
1.5	26	12.50
2	26	12.50

Revision History

Version No.	Date	Description
1.0	Aug 25, 2022	Preliminary datasheet
2.0	September 28,2024	Product upgrades

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